

In the Claims:

Please enter new claims 29 - 32 as shown below in clean copy form:

29. A power processing device comprising:

- a) a multilayer printed circuit board having multiple layers of dielectric sheets; and
- b) a transformer having
 - 1) a core extending through said layers of dielectric sheets, and
 - 2) a first set of electrically conductive windings, at least one of said windings of said first set of electrically conductive windings contained between two adjoining layers of said dielectric sheets, and at least one of said windings positioned on an external surface of said multilayer printed circuit board.

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30. The power processing device according to claim 29, further including a first shielding layer disposed on an exterior surface of said multilayer printed circuit board.

31. The power processing device according to claim 29, further including an electrically conductive trace contained between two of said layers of dielectric sheets, said electrically conductive trace communicating with said first set of electrically conductive windings.

32. The power processing device according to claim 31, further including at least one component secured to an exterior surface of said multilayer printed circuit board at a location over said electrically conductive trace.

In the Claims:

New claims 29 - 32 have been added as shown below in marked up form:

--29. A power processing device comprising:

- a) a multilayer printed circuit board having multiple layers of dielectric sheets; and
- b) a transformer having
 - 1) a core extending through said layers of dielectric sheets, and
 - 2) a first set of electrically conductive windings, at least one of said windings of said first set of electrically conductive windings contained between two adjoining layers of said dielectric sheets, and at least one of said windings positioned on an external surface of said multilayer printed circuit board.

30. The power processing device according to claim 29, further including a first shielding layer disposed on an exterior surface of said multilayer printed circuit board.

31. The power processing device according to claim 29, further including an electrically conductive trace contained between two of said layers of dielectric sheets, said electrically conductive trace communicating with said ~~first set~~ of electrically conductive windings.

32. The power processing device according to claim 31, further including at least one component secured to an exterior surface of said multilayer printed circuit board at a location over said electrically conductive trace.--

REMARKS

This is in response to the Office Action mailed February 11, 2002. Applicant acknowledges the allowance of claims 1 - 23.

A Supplemental IDS is enclosed. The IDS cites a publication that was brought to Applicant's attention on February 25, 2002. The copy provided is the best available to the Applicant. It is offered that Figure 3 of the publication may be similar to Figure 1 of Baarman et al., U.S. Patent No. 6,069,548 ("Baarman"), though this cannot be determined. Baarman is not prior art, but is submitted for the Examiner's convenience in the aforementioned regard.

As a result of a telephone conversation with the Examiner, Applicant now understands that the Examiner is asserting that claims 16 - 19, which are indicated in Applicant's file as having been part of a preliminary Amendment, were never entered. The rejected claims 24 - 28 therefore correspond to the claims numbered 28 - 32 in Applicant's "Collection of Claims," apparently mailed on or about August 4, 2000. New claims 29 - 32 add back the subject matter of originally numbered claims 16 - 19.